

## Device Selection Guide

Code	Chip Materials	Emitted Color	Resin Color
G6	AlGaInP	Brilliant Yellow Green	Water Clear
S2	AlGaInP	Brilliant Orange	

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Code	Rating	Unit
Reverse Voltage	$V_R$		5	V
Forward Current	$I_F$	G6	25	mA
		S2	25	
Peak Forward Current (Duty 1/10 @1KHz)	$I_{FP}$	G6	60	mA
		S2	60	
Power Dissipation	$P_d$	G6	60	mW
		S2	60	
Electrostatic Discharge	$ESD_{HBM}$	G6	2000	V
		S2	2000	
Operating Temperature	$T_{opr}$		-40 ~ +85	°C
Storage Temperature	$T_{stg}$		-40 ~ +90	°C
Soldering Temperature	$T_{sol}$		Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

### Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Code	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	G6	30.0	-----	60.0	mcd	
		S2	90.0	-----	180.0		
Viewing Angle	2θ <sub>1/2</sub>		-----	130	-----	deg	
Peak Wavelength	λ <sub>p</sub>	G6	-----	575	-----	nm	
		S2	-----	611	-----		
Dominant Wavelength	λ <sub>d</sub>	G6	568.5	-----	574.5	nm	I <sub>F</sub> =20mA
		S2	602.0	-----	608.0		
Spectrum Radiation Bandwidth	Δλ	G6	-----	20	-----	nm	
		S2	-----	17	-----		
Forward Voltage	V <sub>F</sub>	G6	1.70	2.00	2.40	V	
		S2	1.70	2.00	2.40		
Reverse Current	I <sub>R</sub>	G6	-----	-----	10	μA	V <sub>R</sub> =5V
		S2	-----	-----	10		

Note:

- 1.Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength±1nm
- 3.Tolerance of Forward Voltage: ±0.1V

## G6

### Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
1	30.0	60.0	mcd	I <sub>F</sub> =20mA

## S2

### Bin Range of Luminous Intensity

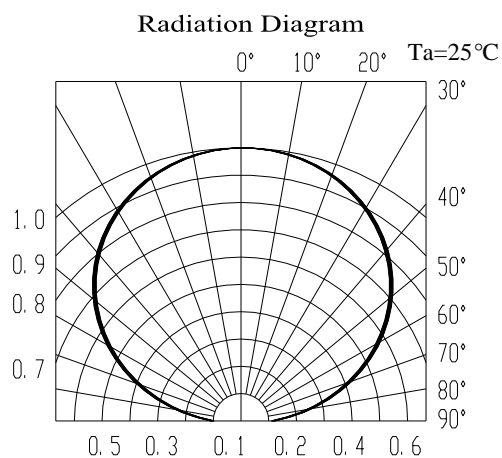
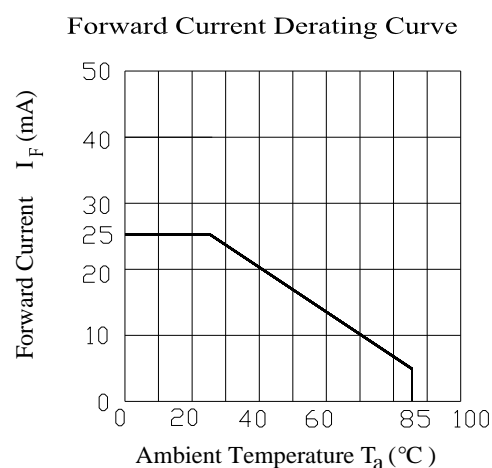
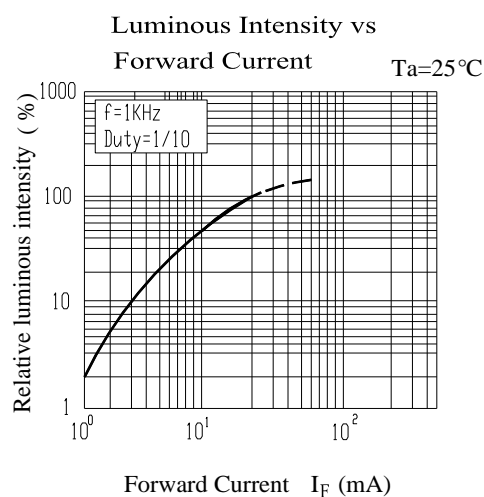
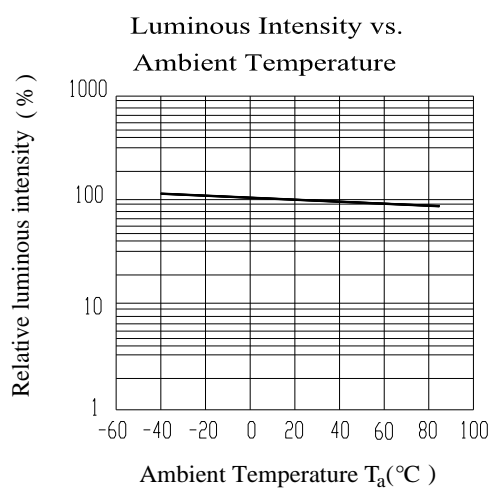
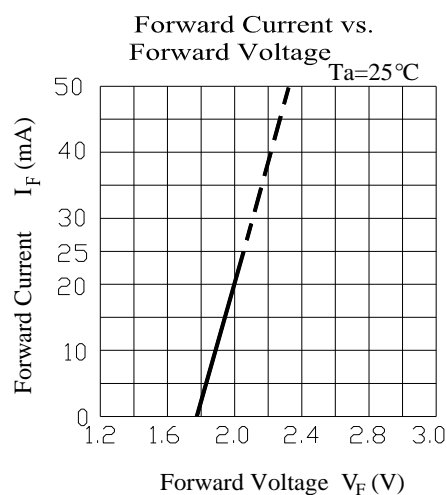
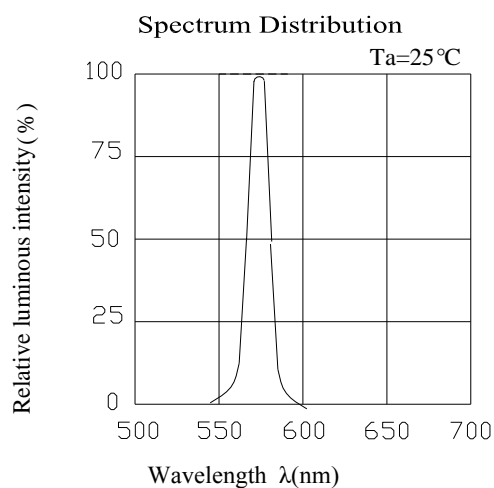
Bin Code	Min.	Max.	Unit	Condition
1	90.0	180.0	mcd	I <sub>F</sub> =20mA

Note:

1.Tolerance of Luminous Intensity: ±11%

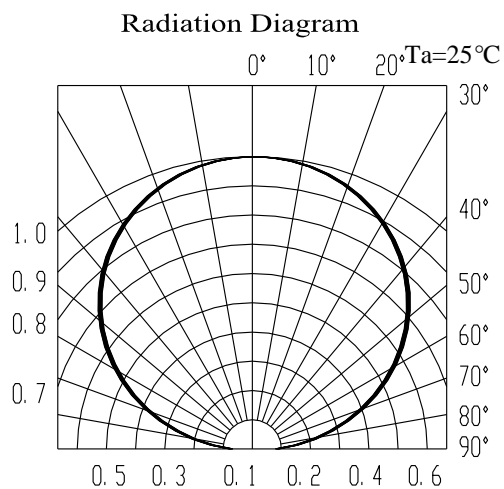
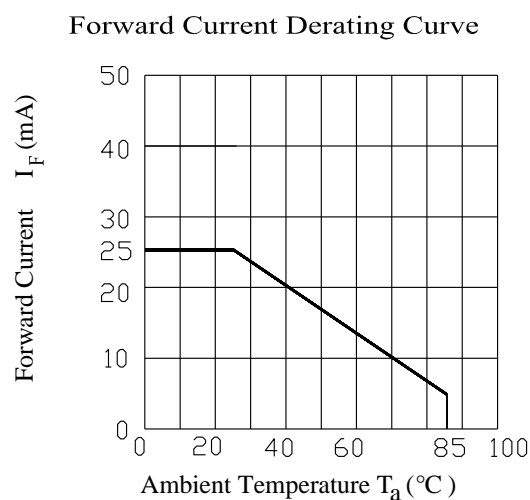
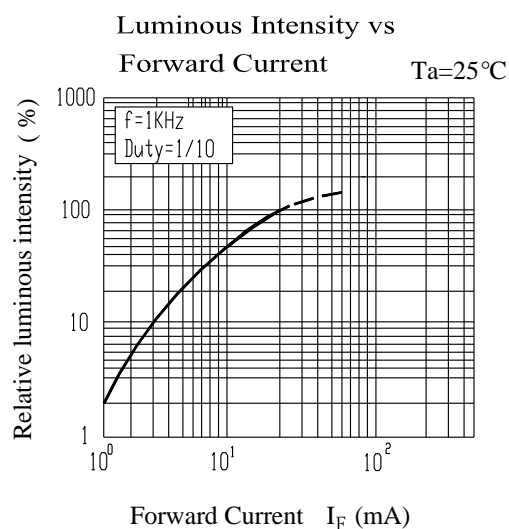
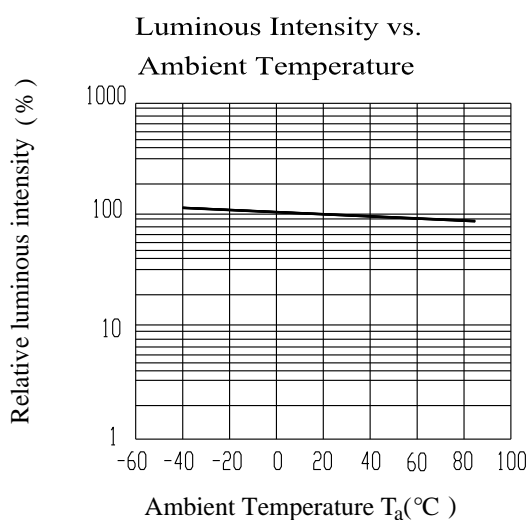
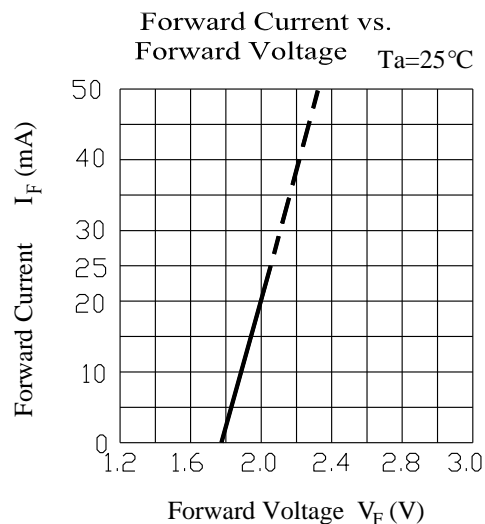
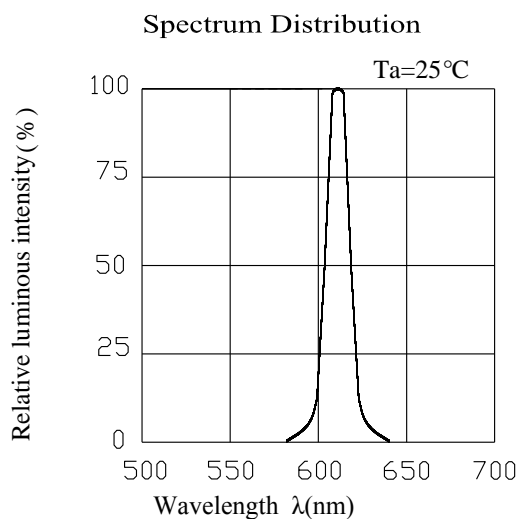
## Typical Electro-Optical Characteristics Curves

G6

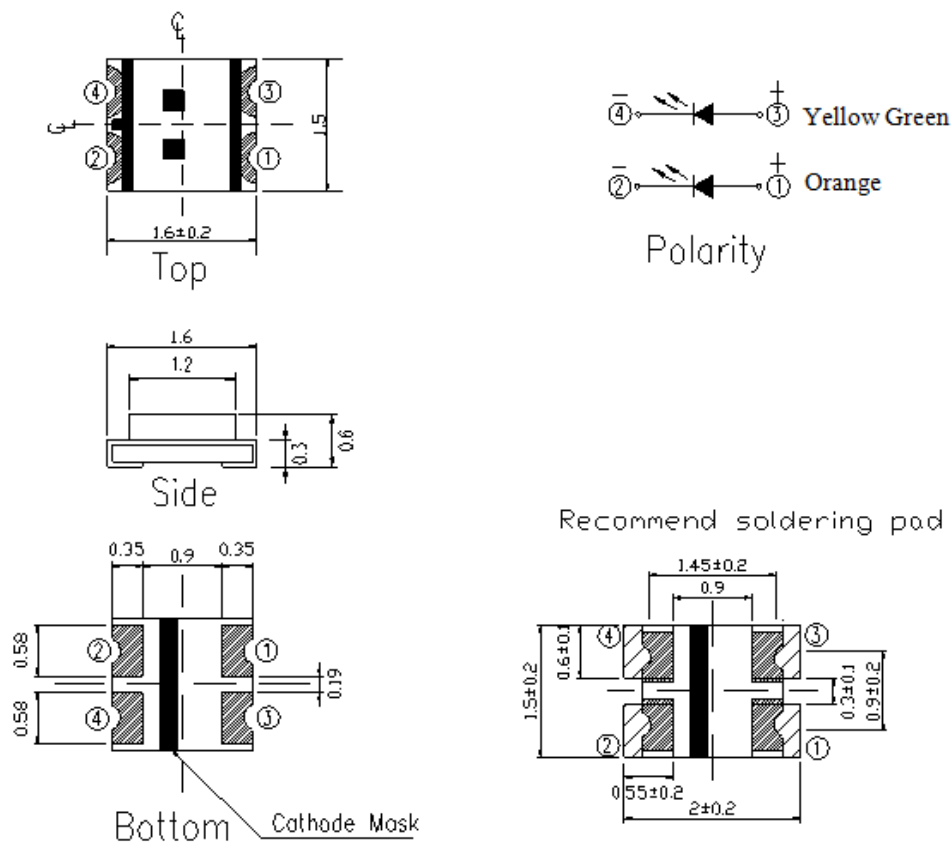


## Typical Electro-Optical Characteristics Curves

S2



## Package Dimension



Suggested pad dimension is just for reference only.  
Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned  $\pm 0.1$  mm. Unit = mm

## Moisture Resistant Packing Materials Label Explanation

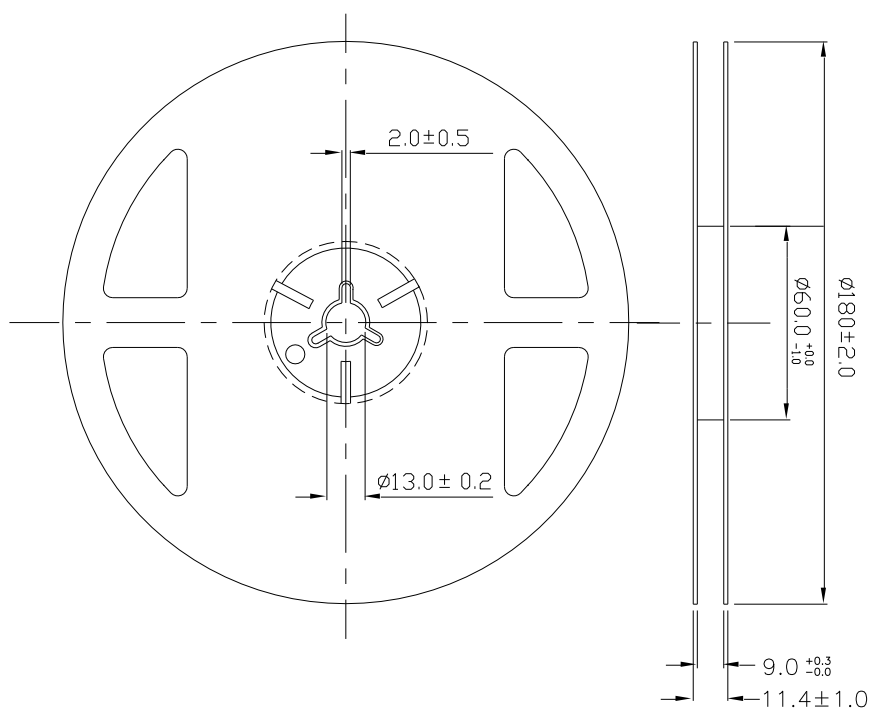
RoHS Pb **EVERLIGHT** **5**

CPN: XXXXXXXXXXXXXXXXXXXX 測試區  
 XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX  
 P/N: XXXXXXXXXXX  
 XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX  
 LOT NO: Y150716XXX-XXXXXXXXXX-XXXXXXXXXX  
 QTY: 0123456789 HUE: XXXXXXXXXXX  
 CAT: XXXXXXXXXXX REF: XXXXXXXXXXX  
 REFERENCE: BTPYYMDDXXXXX  
 MSL-X MADE IN TAIWAN



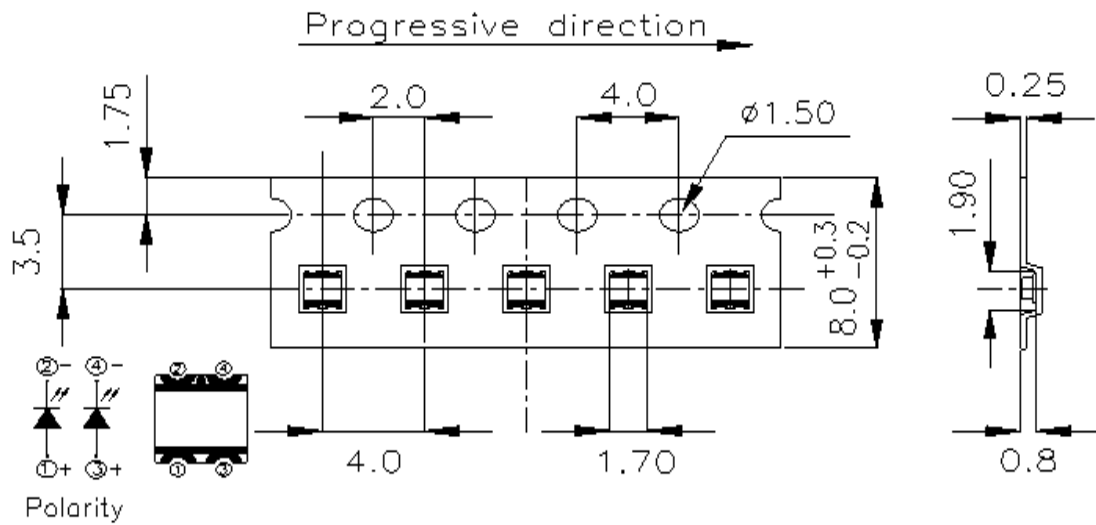
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

## Reel Dimensions



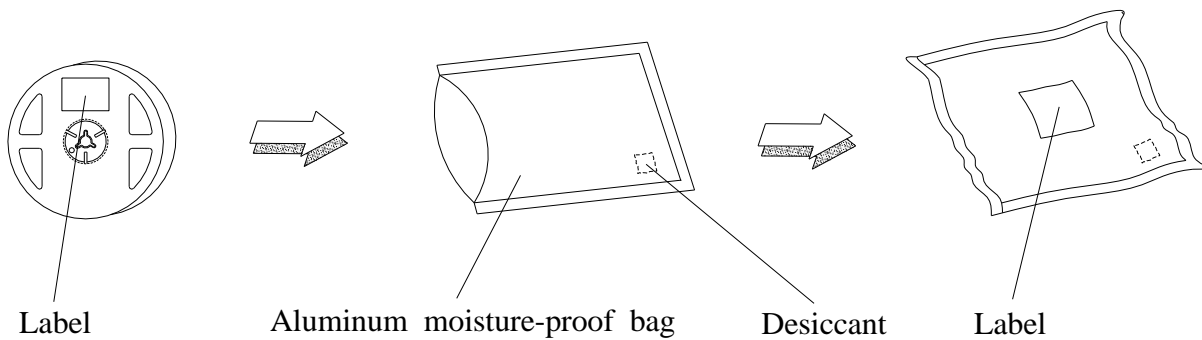
Note: The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Unit = mm

### Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Unit = mm

### Moisture Resistant Packaging





## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 After opening the package: The LEDs should be kept at 30°C or less and 60%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

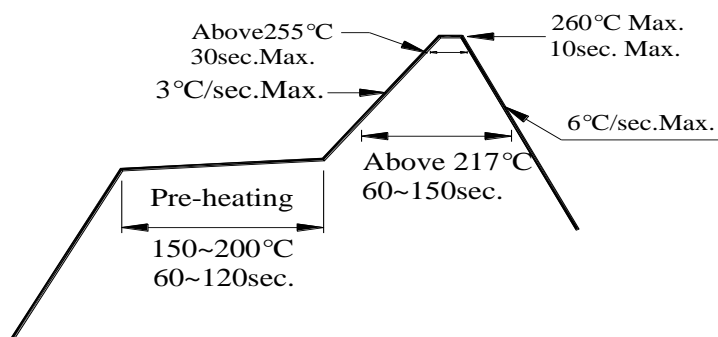
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

### 3. Soldering Condition

#### 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

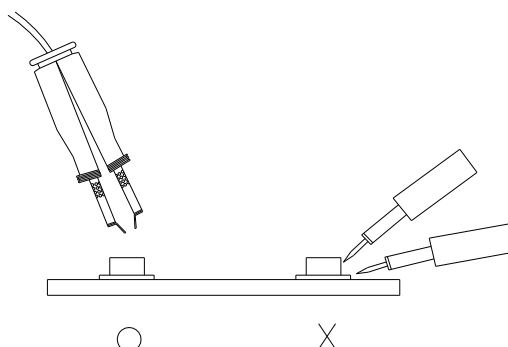
3.4 After soldering, do not warp the circuit board.

### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



## Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.